

MOS

Si/SiO₂

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(2014/5/ 5 2013/ 12 /11)

MOS
Si(111) (5-20)min 600°C
SiO₂ Si/SiO₂
.FTIR (Si-O-Si) (1079cm⁻¹)
(I-V) (C-V) (ac) (f >5kHz)
MOS (I-V) .
.15min 0.4 volt 0.6 volt (5,10) min
.0.2 volt (20) min
Si/SiO₂ SiO₂ CO₂ :

The Effect of Si/SiO₂ Interface on the Electrical Properties of MOS Device with Nano Layer Silicon Dioxide Grown by Induced Laser Oxidation

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ABSTRACT

In this work a MOS device was fabricated with nano dioxide layer on silicon using a laser induced oxidation technique, at 600°C temperature for different times oxidation (5-20) min. FTIR spectrums were studied and analyzed for the Si (111) substrate, the Si/SiO₂ interface and the SiO₂ layer.

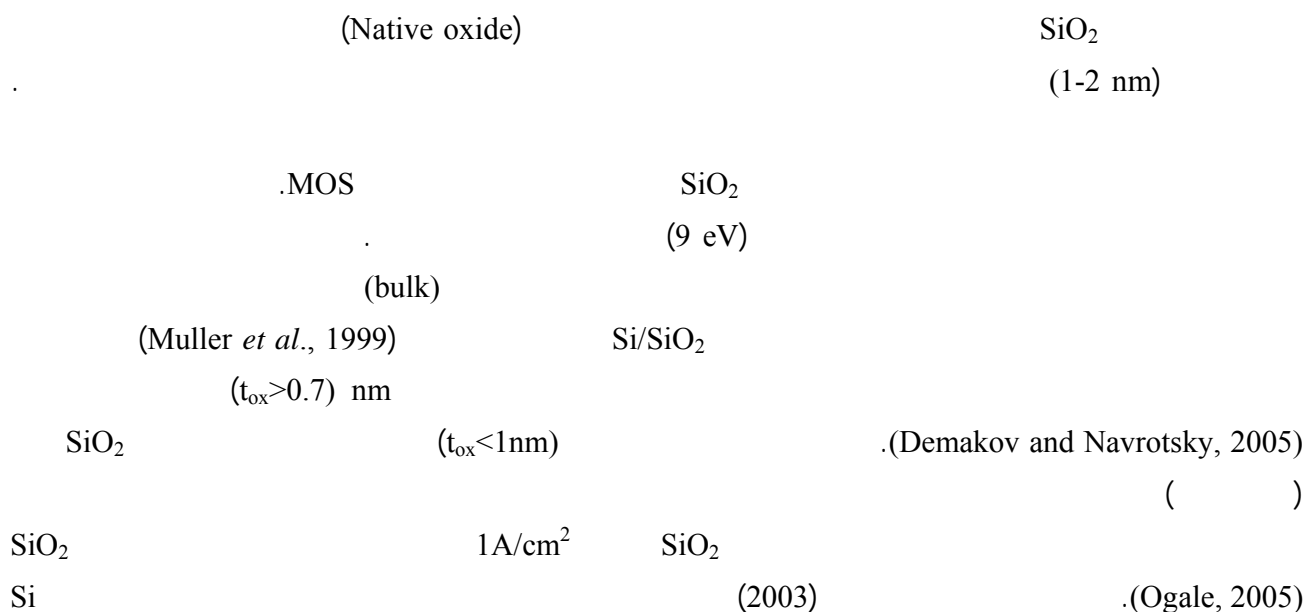
The results gave a characteristic sharp peak presence at the wave number (1079 cm^{-1}) corresponding to the level of elongation vibration (Si-O-Si) which consists the required oxide.

The electrical measurement results show the response of the MOS device for the (C-V) and (I-V) characteristics. The capacity was inhomogeneous at the interface between insulator and semiconductor because of the (ac) signal harmony, as an extra-capacity created depending on the frequency, while it does not appear at frequency ($f > 5\text{kHz}$). This determines the nature of the electronic response of the device.

The different times for the oxide configuration gives a different value for the capacity that's where the capacity increases with the time of laser induction oxidation increase. The oxide thickness has an inverse relationship with the time of laser induction of the oxidation.

The (I-V) characteristics show the MOS devices fabricated with oxidation time at (5,10) min has leakage current started after 0.6 volt, where the devices which oxidized for 15 min has leakage current at 0.4 volt, but the leakage current begun at 0.2 volt for the devices with 20 min oxidation time.

Keywords: CO₂ laser, silicon dioxide, Si/SiO₂ interface



Si

(El-Kareh, 2009)

..... Si/SiO₂

.(Saadon, 2012)

SiO₂ (2005)

(I-V)

oxidation selective

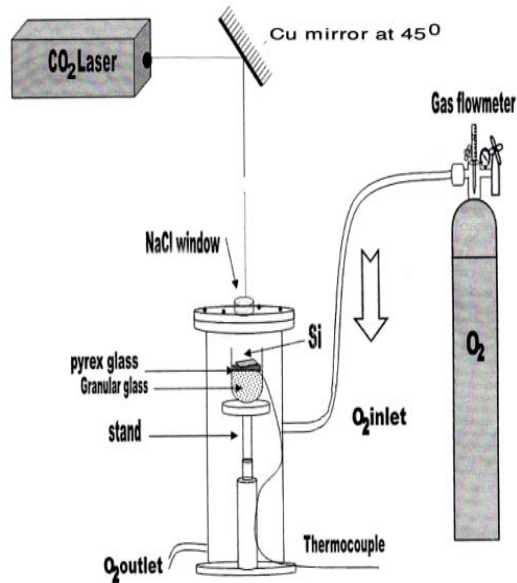
0.86nm MOS

(Hess and Lambers, 2004; Kailath *et al.*, 2009)

SiO₂ MOS
(I-V), (C-V) FTIR

p-type Si(111) (substrates)

1.3Ω.cm



:1

:

CO₂ SiO₂
(1) (10.6 μm) (22)

.(NaCl)

CO₂ 22 watt (10)Amp
(1) NaCl 45°

.(Chung, 2007) (150watt/m.K)

: CO₂

: .(Chung, 2007)

(Chung, 2007; Koren, 1985)

(1) lit/min

CO₂

600 °C

.(5,10,15 and 20) min

.FTIR

(Razeghi, 2006)

SiO₂

$$X_o = \frac{A_g \epsilon_{ox} \epsilon_o}{C_{ox}} \dots\dots\dots(1)$$

(7.85×10⁻⁷)m²

A_g

C_{ox}

.(8.85x10⁻¹²)F/m

ε_o (3.9)

ε_{ox}

MOS

10⁻

(Varian 3317)

99.9%

(1 mm)

.4torr

SiO₂

(-) (-)

(ac) 10kHz 5kHz

(1-10) kHz

MOS

(-)

(dc)

(0.22 μF)

(50 mvolt p.p)

:

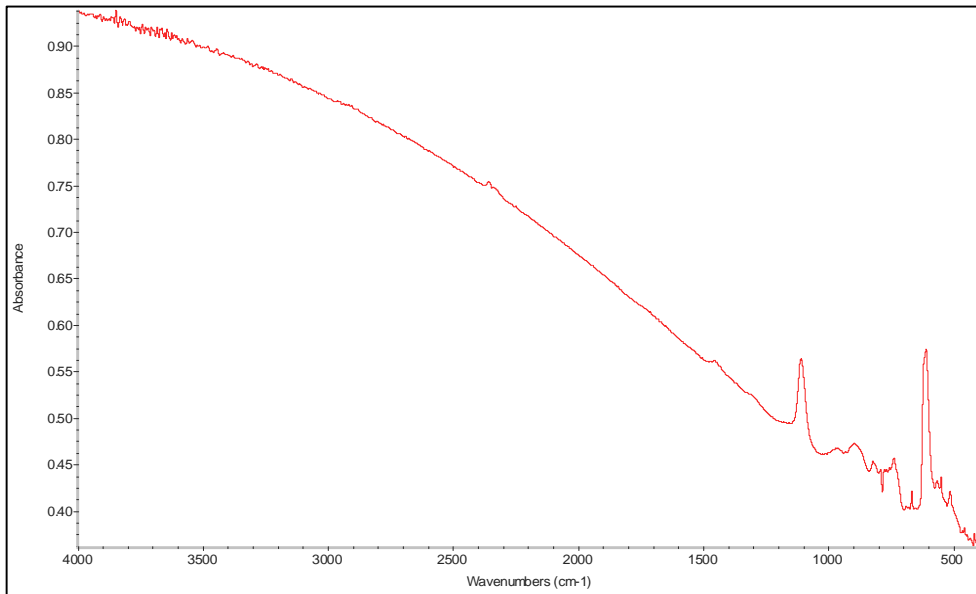
$$C = \frac{I}{2 \pi f V_g} \dots\dots\dots(2)$$

..... Si/SiO₂

(P) Si(111) FTIR
FTIR (2)
(Si-O) (1070 -1080) cm⁻¹

Si(100)

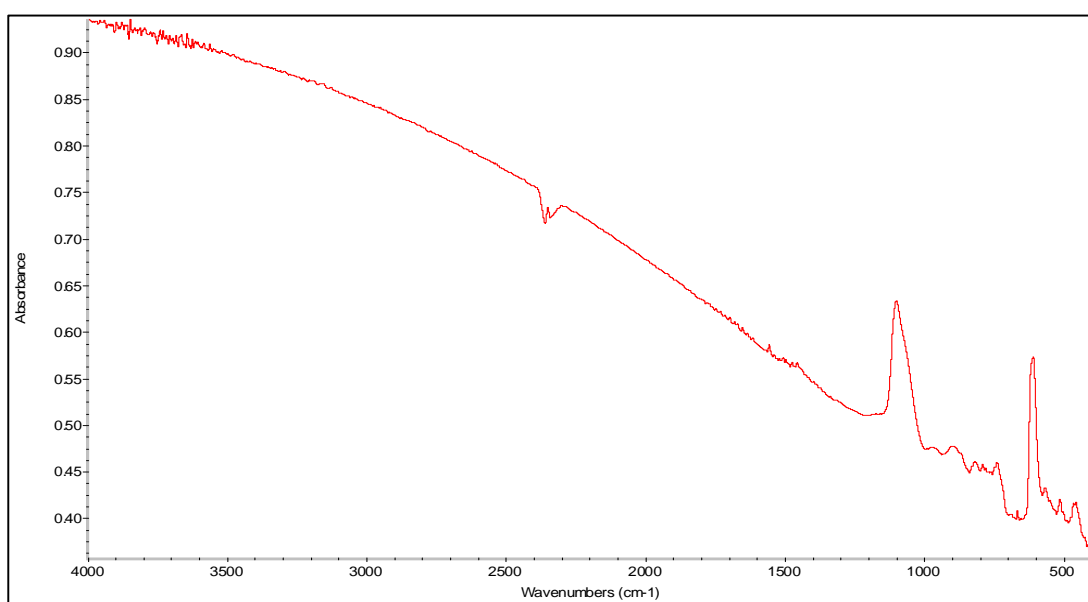
p Si(111)



p Si(111) FT-IR :2

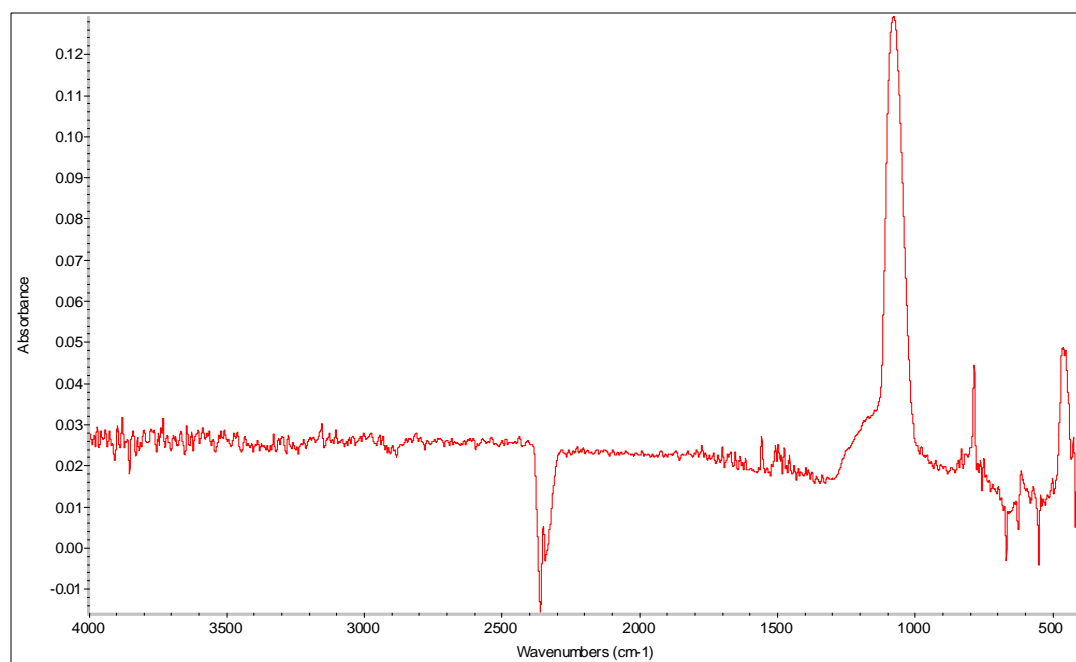
.(Si-O) (Clean room)

(3) Si/SiO₂ FT-IR (3)
p Si(111) (1070 -1080) cm⁻¹
CO₂ SiO₂
.Si-Si (600)cm⁻¹

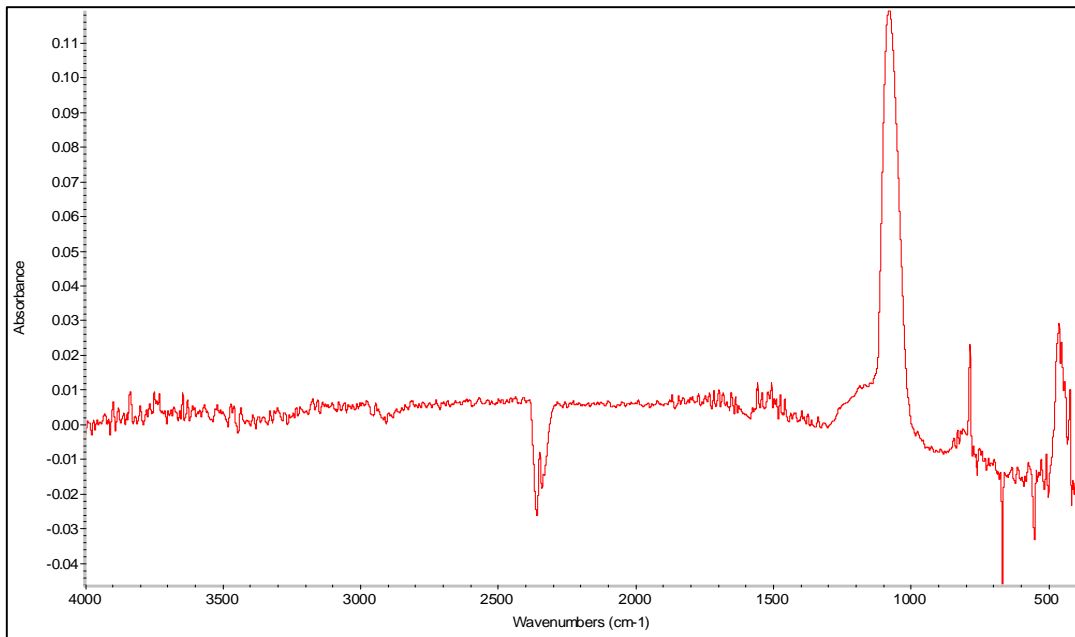


Si/SiO₂ FT-IR :3

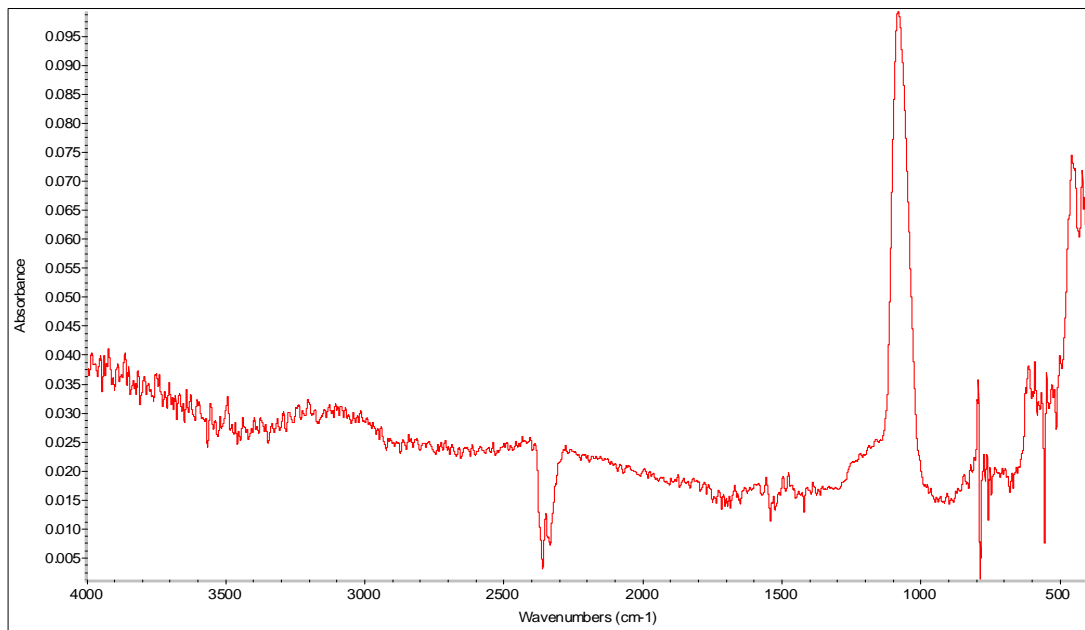
| | | | | |
|-----------------|-----------------------------|--------------|------------------------|----------------------------|
| | SiO₂ | FT-IR | SiO₂ | FT-IR |
| CO ₂ | | | | |
| FT-IR | (4 - 7) | | (4-7) | ((5,10,15 and 20) min) |
| | (950 -1350)cm ⁻¹ | IR | | (400-4000)cm ⁻¹ |



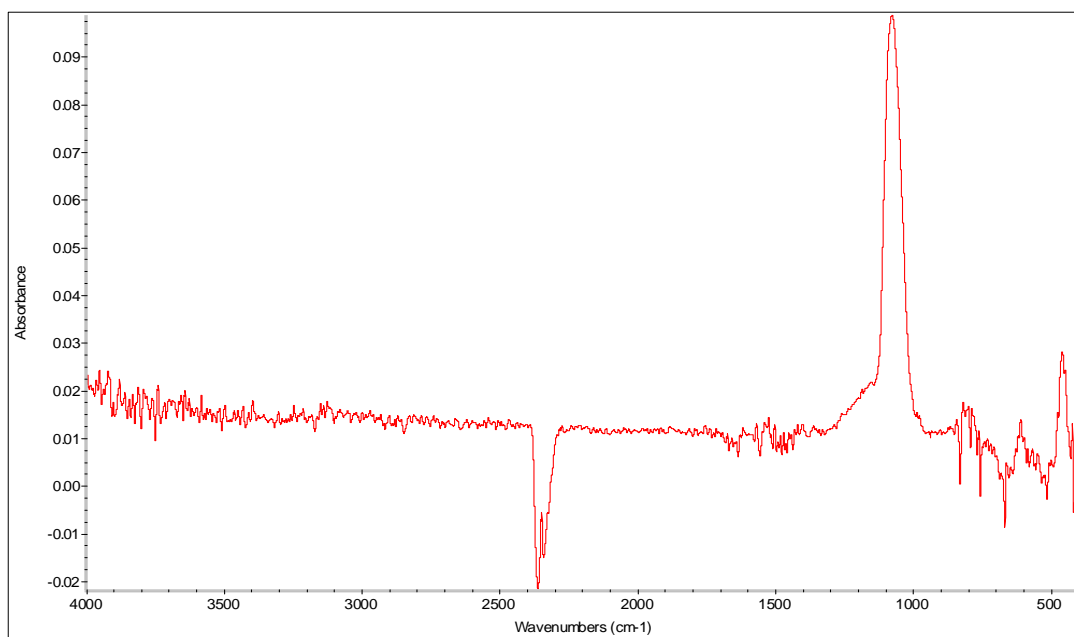
(5min) SiO₂ FTIR :4



(10min) SiO₂ FTIR : 5



(15min) SiO₂ FTIR : 6



(20min) SiO₂ FTIR :7

.(Lambers and Hess, 2003)

(Si-O-Si)

: (4-7)

(Tsuji *et al.*, 1991; Takoa *et al.*, 2007)

(~1079)cm⁻¹

-1

(Si-O-Si)

.(Lucovsky and Irene, 1987; Lambers and Hess, 2003)

(950) cm⁻¹

-2

.(Maruyama and Shirai, 1993) (Si-OH)

(~1200) cm⁻¹

()

-3

.(Hess and Lambers, 2004)

(~1079) cm⁻¹

(4-7)

(~1079) cm⁻¹

(Lambers and Hess, 2003)

MOS (-)

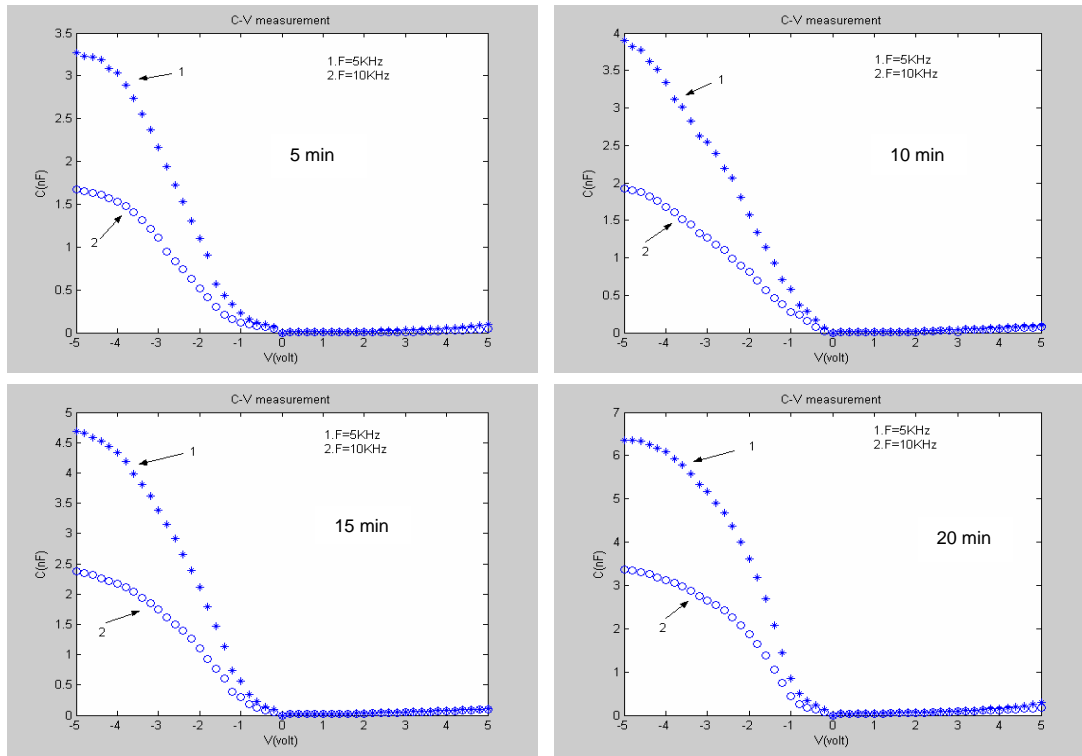
SiO₂

MOS (-)

.(8)

(5,10,15 and 20) min

(600)C°



(5,10,15 and 20) min

SiO₂

MOS

(C-V)

:8

(8)

.(Tataroglu *et al.*, 2005; Tataroglu and Altindal, 2006)

(ac)

(ac)

(f>5kHz)

.(Tataroglu *et al.*, 2006)

MOS (-)

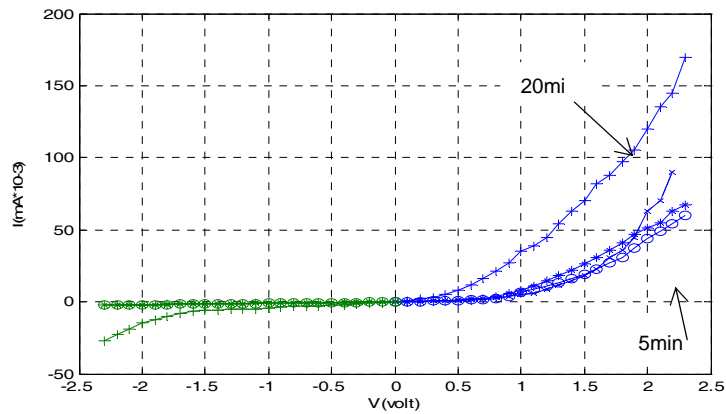
SiO₂

MOS (-)

.(9)

(5,10,15 and 20) min

600°C

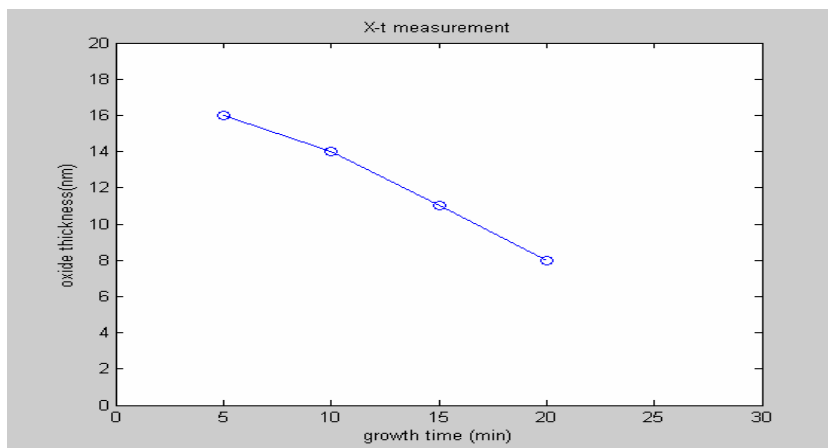


(20-15-10-5)min SiO₂ MOS (I-V) :9

(14-16nm) (5,10) min MOS (9)
 .15 min 0.4 volt 0.6 volt
 .02 volt (20) min
 9 eV SiO₂ (5-10) min
 Si/SiO₂ FT-IR
 (9)

(1990)

(10)



:10

111

.....

Si/SiO₂

(10)

.SiO₂

SiO₂

0.1eV

SiO₂ Si₂O SiO

.(Kailath *et al.*, 2009 ; Singh *et al.*, 2004)

.(Osipov *et al.*, 2006)

1100 cm⁻¹

1000 cm⁻¹

FT-IR

SiO₂

.(Lambers and Hess, 2003)

(I-V) (C-V)

.(f > 5kHz)

(f ≤ 5kHz)

.(2005)

. 20-12 (1)16

.MOS

(1)14 .

.(2003)

.101 -92

.(1990)

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